

This listing of claims will replace all prior versions of claims in the Application.

Listing of Claims

Claim 1. (Currently Amended) A method of providing a metal seed layer substantially free of discontinuities disposed on a substrate comprising the step-steps of contacting a metal seed layer having discontinuities disposed on a substrate with an electroplating bath comprising a) a source of metal ions; b) an electrolyte comprising two ~~or more~~ acids; c) and optionally one or more additives; wherein the two acids are present in a ratio of 99:1 to 1:99 by weight; and applying a current.

Claim 2. (Currently Amended) The method of claim 1 wherein the two or more acids are selected from organic acids, inorganic acids, ~~or~~ and mixtures thereof.

Claim 3. (Currently Amended) The method of claim 2 wherein the organic acids are selected from alkylsulfonic acids, aryl sulfonic acids, carboxylic acids ~~or~~ and halogenated acids.

B3. Claim 4. (Currently Amended) The method claim 2 wherein the inorganic acids are selected from sulfuric acid, phosphoric acid, nitric acid, hydrogen halide acids, sulfamic acid ~~or~~ and fluoroboric acid.

Claim 5. (Currently Amended) The method of claim 1 wherein the ~~two or more~~ acids are present in ~~an~~ a total amount of from about 1 to about 350 g/L.

Claim 6. (Original) The method of claim 1 wherein the source of metal ions is a source of copper ions.

Claim 7. (Currently Amended) The method of claim 6 wherein the source of copper ions is selected from copper sulfates, copper acetates, copper fluoroborate, ~~or~~ and cupric nitrates.

Claim 8. (Original) The method bath of claim 6 wherein the source of copper ions is present in an amount of from about 1 to about 300 g/L.

Claim 9. (Original) The method of claim 1 wherein the electrolyte further comprises a source of halide ions.

Claim 10. (Currently Amended) A method of manufacturing an electronic device comprising the step-steps of contacting a metal seed layer having discontinuities disposed on a

substrate with an electroplating bath comprising a) a source of metal ions; b) an electrolyte comprising two ~~or more~~ acids; c) and optionally one or more additives; wherein the two acids are present in a ratio of 99:1 to 1:99 by weight; and applying a current.

Claim 11. (Currently Amended) The method of claim 10 wherein the two or more acids are selected from organic acids, inorganic acids, ~~or~~ and mixtures thereof.

Claim 12. (Currently Amended) The method of claim 11 wherein the organic acids are selected from alkylsulfonic acids, aryl sulfonic acids, carboxylic acids ~~or~~ and halogenated acids.

Claim 13. (Currently Amended) The method claim 11 wherein the inorganic acids are selected from sulfuric acid, phosphoric acid, nitric acid, hydrogen halide acids, sulfamic acid ~~or~~ and fluoroboric acid.

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Contd. Claim 14. (Currently Amended) The method of claim 10 wherein the ~~two or more~~ acids are present in ~~an~~ a total amount of from about 1 to about 350 g/L.

Claim 15. (Original) The method of claim 10 wherein the source of metal ions is a source of copper ions.

Claim 16. (Currently Amended) The method of claim 15 wherein the source of copper ions is selected from copper sulfates, copper acetates, copper fluoroborate, ~~or~~ and cupric nitrates.

Claim 17. (Original) The method bath of claim 15 wherein the source of copper ions is present in an amount of from about 1 to about 300 g/L.

Claim 18. (Original) The method of claim 10 wherein the electrolyte further comprises a source of halide ions.

Claims 19-22. (Canceled)

Claim 23. (New) The method of claim 1 wherein the electroplating bath comprises three or more acids.

Claim 24. (New) The method of claim 10 wherein the electroplating bath comprises three or more acids.
